



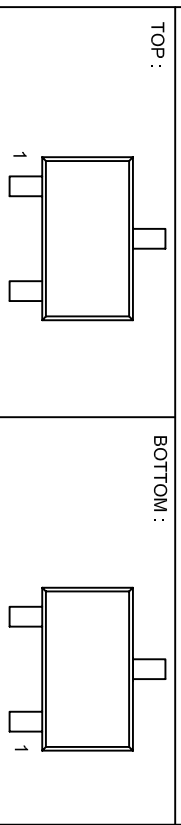
**PRODUCT INFORMATION**

Customer :	
Device :	Device ID :
Die Size :	Wafer Material :
Package Type:	No. of Wires :
3L SOT-23	

**MATERIAL INFORMATION**

Leadframe :	Pad Size :
Epoxy :	Wire size :
Molding Compound :	Lead Finish :
A194 with Ag spot plating	
27x36 mils	

**MARKING INSTRUCTION**



BONDING DIAGRAM NO.

REF. BONDING DIAGRAM NO.

SCALE  
not to scale

DRAWN BY: \_\_\_\_\_ REVIEWED BY: \_\_\_\_\_

REVISION NO.		APPROVALS		
REV. #	DESCRIPTION	PCN #	DEPT	DATE
			CUST	
			QSM	
			QC	
			MFG	

SPECIAL INSTRUCTIONS :

